

**DESCRIPTION**

The AM20N06-Q is available in PDFN8(3.3x3.3) Package.

BVDSS	RDSON	ID
60V	30mΩ	20A

**APPLICATION**

- Valves control
- Solenoids control
- Lighting

**ORDERING INFORMATION**

Package Type	Part Number	
PDFN8(3.3x3.3) SPQ: 5,000pcs/Reel	PJ8S	AM20N06PJ8SR-Q
		AM20N06PJ8SVR-Q
Note	R: Tape & Reel Q: AEC-Q101 Certificated V: Halogen free Package	
AiT provides all RoHS products		

**ABSOLUTE MAXIMUM RATINGS**

T<sub>A</sub>=25°C, unless otherwise noted.

V <sub>DS</sub> , Drain-Source Voltage	60V
V <sub>GS</sub> , Gate-Source Voltage	±20V
I <sub>D</sub> , Continuous Drain Current (1)	20A
I <sub>DM</sub> (1), Drain Current- Pulsed	80A
P <sub>D</sub> , Total Power Dissipation   T <sub>C</sub> =25°C	44W
E <sub>AS</sub> (2), Single Pulse Avalanche Energy	56mJ
T <sub>STG</sub> , Storage Temperature Range	-55°C~+175°C
T <sub>J</sub> , Operating Junction Temperature Range	-55°C~+175°C
R <sub>θJC</sub> , Thermal Resistance Junction-Case	3.4°C/W

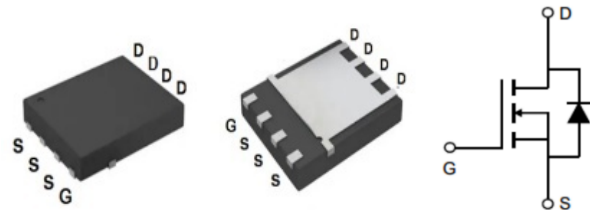
Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

(1) Repetitive Rating: Pulse width limited by maximum junction temperature.

(2) E<sub>AS</sub> condition : T<sub>J</sub>=25°C, V<sub>DD</sub>=30V, V<sub>GS</sub>=10V, L=0.5mH, R<sub>g</sub>=25Ω

**FEATURE**

- V<sub>DS</sub> = 60V, I<sub>D</sub> = 20A  
R<sub>DS(ON)</sub> < 30mΩ @ V<sub>GS</sub>=10V  
R<sub>DS(ON)</sub> < 40mΩ @ V<sub>GS</sub>=4.5V
- High ESD Capability
- High Density Cell Design for Lower R<sub>DS(ON)</sub>
- 175°C Operating Temperature
- Good Stability and Uniformity with High EAS
- AEC-Q101 certificated

**PIN DESCRIPTION**

PDFN8 (3.3 x 3.3)

Pin#	Symbol	Function
1, 2, 3,	S	Source
4	G	Gate
5, 6, 7, 8	D	Drain

**ELECTRICAL CHARACTERISTICS**T<sub>A</sub>=25°C, unless otherwise noted.

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
<b>OFF Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> = 0V	-	-	±100	nA
<b>ON Characteristics</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.3	1.8	2.3	V
Drain-Source On-State Resistance (1)	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =25A	-	25	30	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =25A	-	30	40	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =10A	-	11	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz	-	670	-	pF
Output Capacitance	C <sub>oss</sub>		-	76	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	66	-	
<b>Switching Characteristics (2)</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V, I <sub>D</sub> =10A, R <sub>GEM</sub> =10Ω, V <sub>GS</sub> =10V	-	19.20	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	6.40	-	
Turn-Off Delay Time	t <sub>d(off)</sub>		-	29.20	-	
Turn-Off Fall Time	t <sub>f</sub>		-	8.20	-	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =48V, I <sub>D</sub> =10A, V <sub>GS</sub> =10V	-	21	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	5	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	6.50	-	
<b>Drain-Source Diode Characteristics</b>						
Drain Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A,	-	-	1.2	V
Reverse Recovery Time	T <sub>rr</sub>	T <sub>j</sub> =25°C , IF=10A ,	-	33.6	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>	di/dt=100A/uS	-	32.1	-	nC

(1) Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.

(2) Guaranteed by design, not subject to production.



## TYPICAL PERFORMANCE CHARACTERISTICS

Fig 1. Output Characteristics

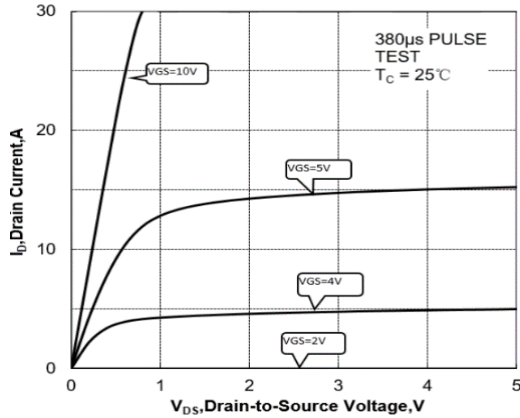


Fig 2. Transfer Characteristics

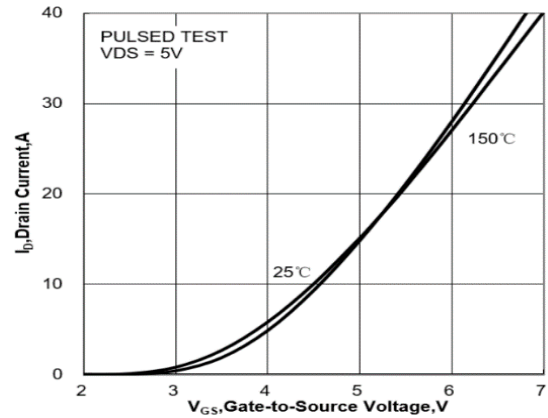


Fig 3. On-Resistance vs.  $I_D$  and  $V_{GS}$

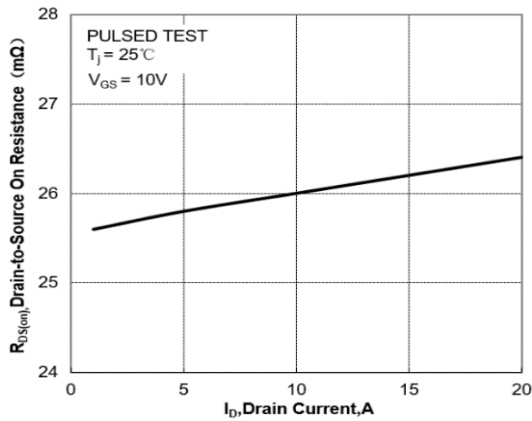


Fig 4. On-Resistance vs. Junction Temperature

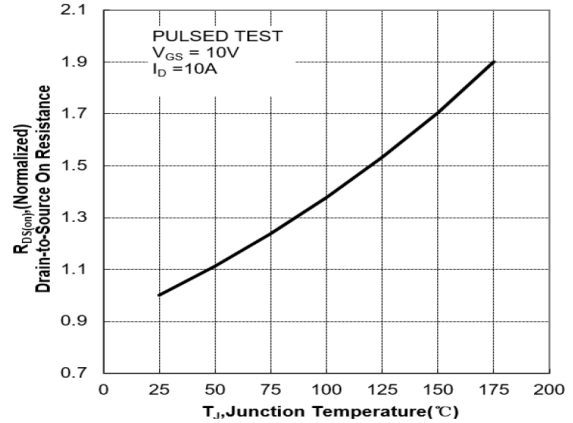


Fig 5. On-Resistance vs.  $V_{GS}$

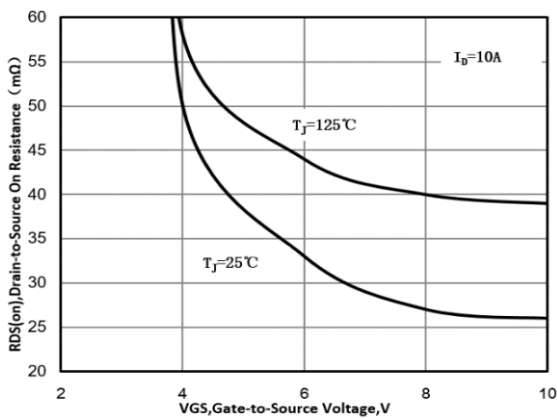


Fig 6. Body Diode Forward Voltage

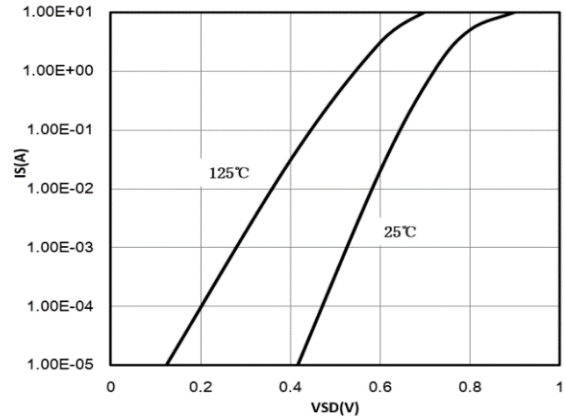




Fig 7. Gate-Charge Characteristics

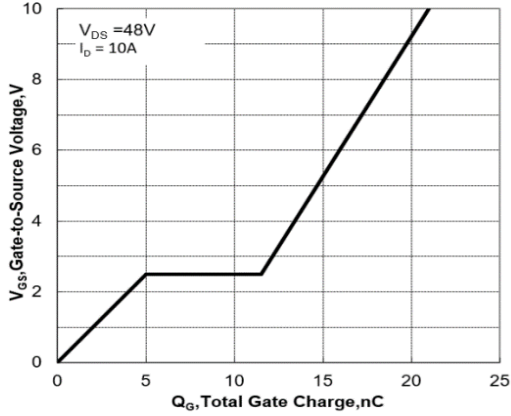


Fig 8. Capacitance Characteristics

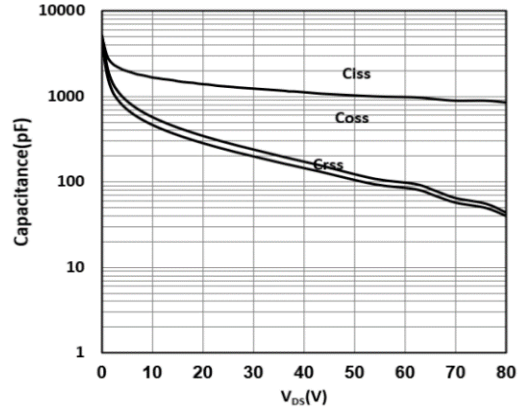


Fig 9. Maximum Forward Biased Safe Operation Area

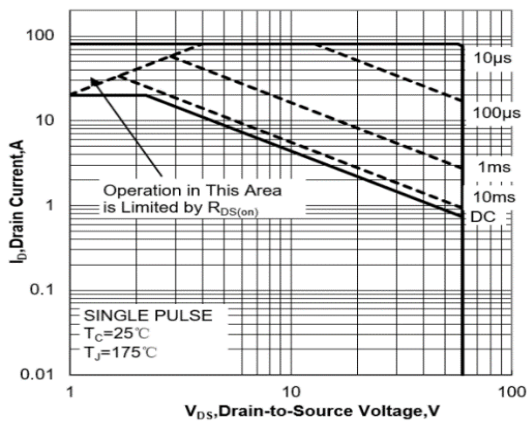


Fig 10. Single Pulse Power Rating Junction-to-Ambient

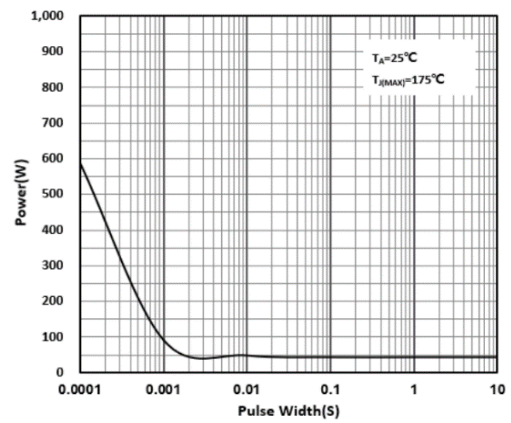


Fig 11. Normalized Maximum Transient Thermal Impedance

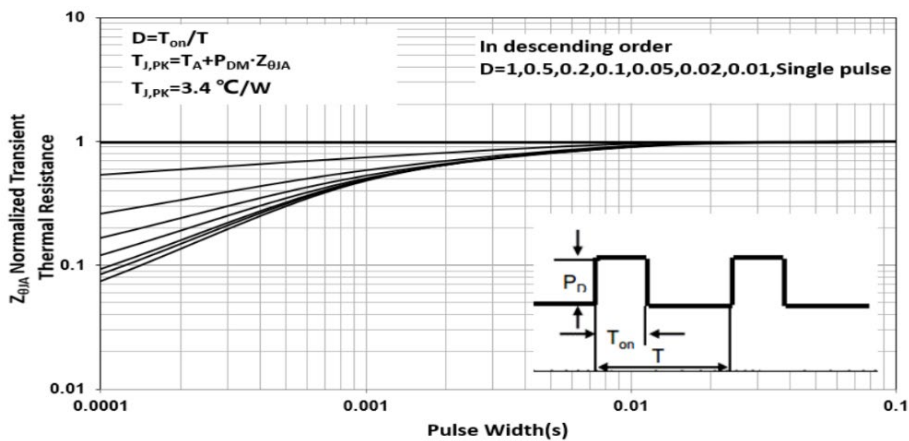




Fig 12. Gate Charge Test Circuit

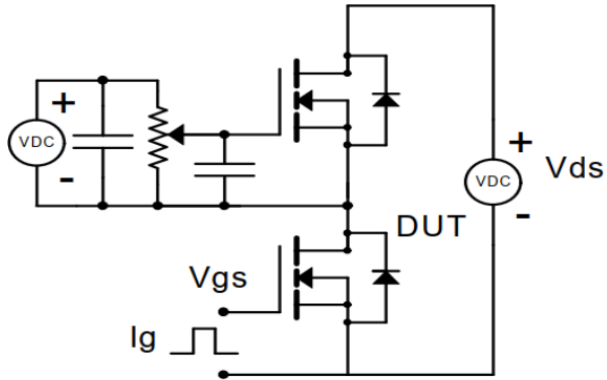


Fig 13. Gate Charge Test Waveform

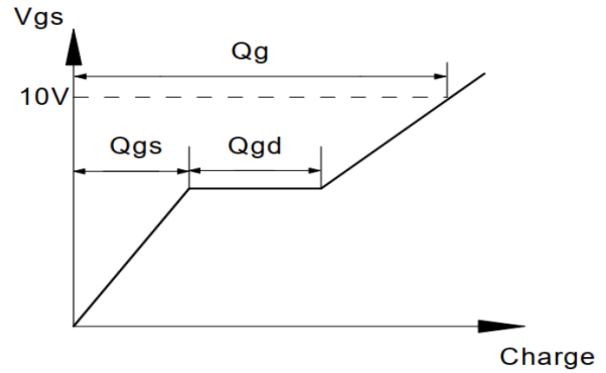


Fig 14. Resistive Switching Test Circuit

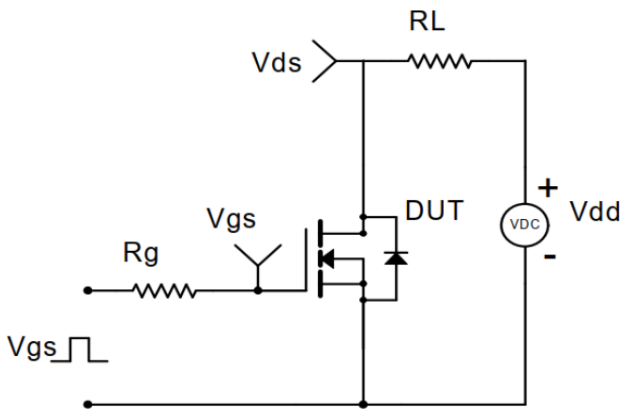


Fig 15. Resistive Switching Test Waveforms

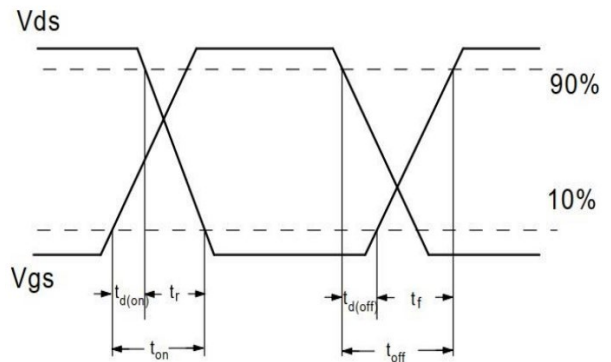


Fig 16. Unclamped Inductive Switching (UIS) Test Circuit

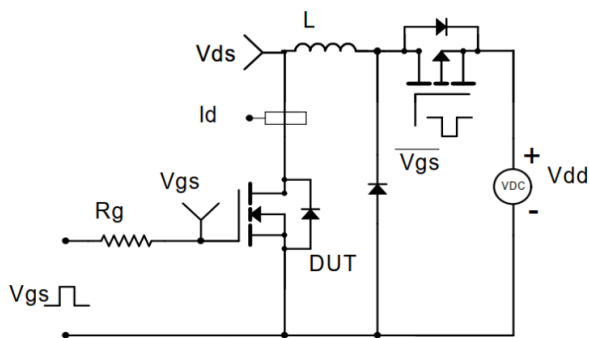


Fig 17. Unclamped Inductive Switching (UIS) Test Waveform

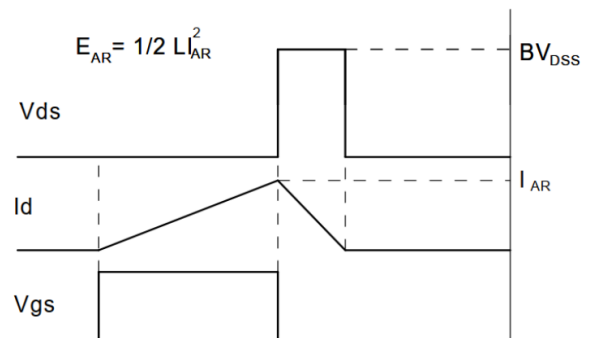




Fig 18. Diode Recovery Test Circuit

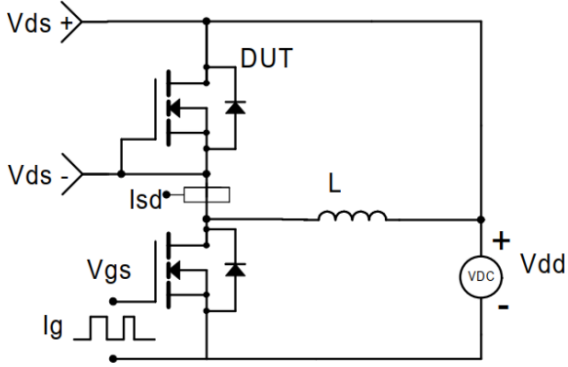
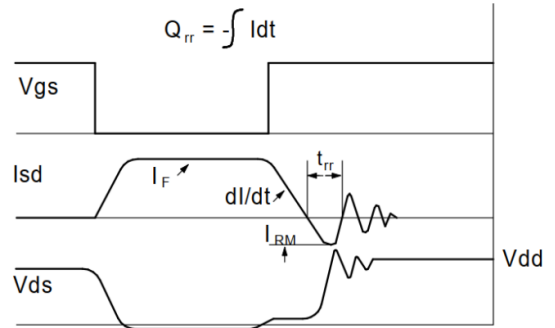


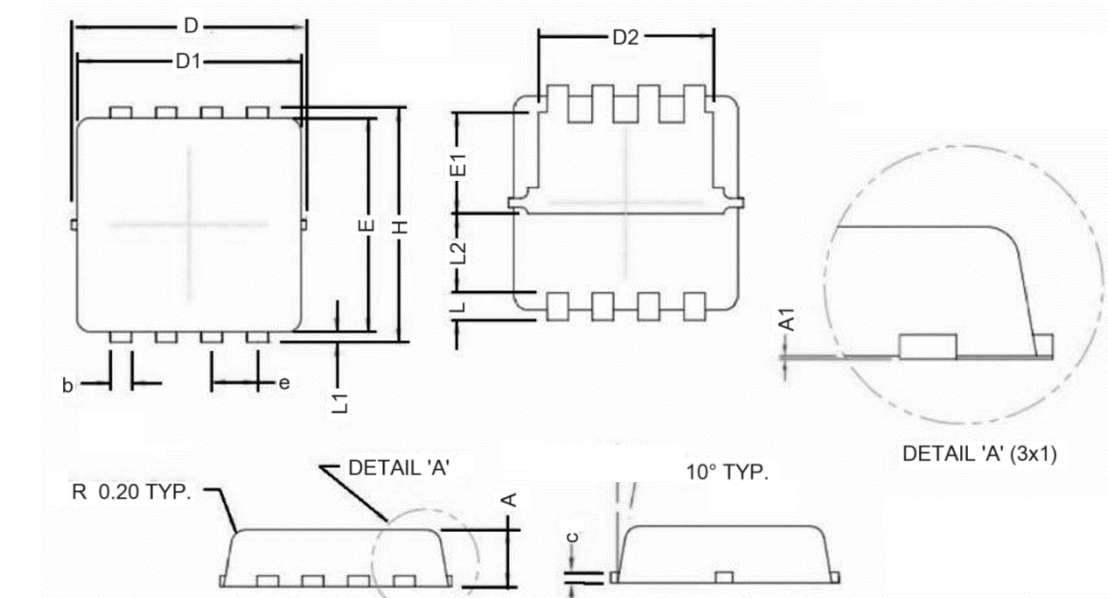
Fig 19. Diode Recovery Test Waveforms





**PACKAGE INFORMATION**

Dimension in PDFN8(3.3x3.3) (Unit: mm)



Symbol	Millimeters (mm)	
	Min.	Max.
A	0.700	0.900
A1	0.000	0.050
b	0.240	0.350
c	0.100	0.200
D	3.250	3.400
D1	3.050	3.250
D2	2.400	2.600
E	3.000	3.200
E1	1.350	1.550-
e	0.650 BSC	
H	3.200	3.400
L	0.300	0.500
L1	0.100	0.200
L2	1.130 REF.	





## IMPORTANT NOTICE

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